

Japan Packaging Committee Meeting Summary and Minutes

SEMI Japan Standards Spring 2014 Meetings
Thursday, March 20, 2014, 15:00-17:00
SEMI Japan, Tokyo, Japan

Next Committee Meeting

SEMI Japan Standards Spring 2014 Meetings
Thursday, May 8, 2014, 15:00-17:00
SEMI Japan, Tokyo, Japan

Table 1 Meeting Attendees

Co-Chairs: Yutaka Koma (Consultant), Masahiro Tsuruya (iNEMI)

SEMI Staff: Naoko Tejima (SEMI Japan)

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
Tokyo Seimitsu	Chiba	Kiyotaka	Shin-Etsu Polymer	Shinozuka	Nobuhiro
Consultant	Koma	Yutaka	Micron Memory Japan	Sonobe	Kaoru
Shin-Etsu Polymer	Maekawa	Mitsunori	Shin-Etsu Polymer	Suzuki	Hideki
Disco	Masuchi	Sumio	Shin-Etsu Polymer	Uchiyama	Hitoshi
Shin-Etsu Polymer	Ohde	Shoko	iNEMI	Tsuruya	Masahiro
AIST	Shimamoto	Haruo	SEMI Japan	Tejima	Naoko

* alphabetical order by last name

Table 2 Leadership Changes

<i>Group</i>	<i>Previous Leader</i>	<i>New Leader</i>
Packages and Packaging Materials Eco-efficiency Task Force was disbanded.	Shoichi Suzuki (Sumitomo Metal Mining) Kazuhiko Nakamura (Consultant)	None
Wafer Shipping Container for Assembly & Packaging Task Force was disbanded.	Yasunori Shimizu (Shimizu Consultant) Kazuhiko Nakamura (Consultant) Tatsuya Yanagawa (Achilles)	None
Thin Chip Handling Task Force was newly set up.	None.	Hideki Suzuki (Shin-Etsu Polymer) Kazuhiko Nakamura (Consultant)
Packaging 5 Year Review Task Force was newly set up.	None.	Masahiro Tsuruya (iNEMI) Kazunori Kato (AiT)

Table 3 Ballot Results

Passed ballots and line items will be forwarded to the ISC Audit & Review Subcommittee for procedural review.

Failed ballots and line items were returned to the originating task forces for re-work and re-balloting.

<i>Document #</i>	<i>Document Title</i>	<i>Committee Action</i>
5636	Revision of SEMI G92-0412, Specification for Tape Frame Cassette for 450mm Wafer	Passed with editorial change

Table 4 Authorized Ballots

<i>Document #</i>	<i>When</i>	<i>SC/TF/WG</i>	<i>Details</i>
5691	Cycle 2, 2014	Thin Chip (Die) Bending Strength Measurement Method Task Force	New Standard: Test Method for Measurement of Chip (Die) Strength by Mean of Cantilever Bending

Approved by GCS on January 30, 2014

Table 5 Authorized Activities

<i>Document #</i>	<i>Type</i>	<i>SC/TF/WG</i>	<i>Details</i>
5691	SNARF	Thin Chip (Die) Bending Strength Measurement Method Task Force	New Standard: Test Method for Measurement of Chip (Die) Strength by Mean of Cantilever Bending

Approved by GCS on January 30, 2014

Table 6 New Action Items (or move to Section 8, Action Item Review)

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
PKG130719-9	Committee Co-chairs	To review all SNARFs and check whether they are written in the right way.
PKG140320-1	SEMI Staff	To forward adjudication result of Doc.#5636 to the ISC A&R Subcommittee for procedural review.
PKG140320-2	SEMI Staff	To report about the MEMS Activities regarding to Packaging at the committee meeting, if any.
PKG140320-3	SEMI Staff	To forward the teleconference information of 3DS-IC Committee at NA Standards Spring 2014 Meetings.
PKG140320-4	SEMI Staff	To submit the new committee charter to JRSC to get their approval.
PKG140320-5	SEMI Staff	To attach the document list of 5year review procedure to the meeting minutes.

1 Welcome, Reminders and Introductions

Masahiro Tsuruya, committee co-chair, called the meeting to order at 15:00. Self-introductions were made followed by the agenda review.

2 Required Meeting Elements

The meeting reminders on program membership requirement, antitrust issues, intellectual property issues and international effective meeting guidelines, were reviewed by SEMI staff, Naoko Tejima.

3 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting held on November 11, 2013.

Motion: To approve the minutes of the previous meeting as written.

By / 2nd: Yutaka Koma (Consultant) / Sumio Masuchi (Disco)

Discussion: None

Vote: 9 in favor and 0 opposed. **Motion passed.**

Attachment: 01_JA_PKG_Previous_Mtg_Minutes_140320

4 SEMI Staff Report

Naoko Tejima gave the SEMI staff report. This report included SEMI Global 2014 Calendar of Events, Global Standards Meeting Schedule, NA Standards Spring 2014 Meetings, 2014 Critical Dates for SEMI Standards Ballots, SEMI Standards Publication, A&R Ballot Review and Contact Information.

Attachment: 02_SEMI_Staff_Report_140320

5 Liaison Reports

5.1 North America 3DS-IC Committee Report

Naoko Tejima briefly reported for the North America 3DS-IC Committee. This report included Leadership, Organization Chart, Task Force Overview, Meeting Information, Document Review Summary, SNARFs, Issued NA 3DS-IC Ballots, Other Current Activities, NA 3DS-IC Spring 2014 Meeting Schedule and Contact information.

Action Item: SEMI staff to report about the MEMS Activities regarding to Packaging at the committee meeting, if any.

Action Item: SEMI staff to forward the teleconference information of 3DS-IC Committee at NA Standards Spring 2014 Meetings.

Attachment: 03_NA_3DS-IC_Comm_Report_140320

5.2 Taiwan 3DS-IC Committee Report

Naoko Tejima briefly reported for the Taiwan 3DS-IC Committee. This report included Organization Chart, Task Force Overview, SNARFs and Contact Information.

Attachment: 04_TW_3DS-IC_Comm_Report_140320

6 Ballot Review

6.1 Doc.#5636, Revision of SEMI G92-0412, Specification for Tape Frame Cassette for 450mm Wafer

This document passed committee review with editorial changes and will be forwarded to the ISC A&R SC for procedural review.

Action Item: SEMI staff to forward adjudication result of Doc.#5636 to the ISC A&R Subcommittee for procedural review.

Attachment: 05_Ballot_Report_for_5636_140320

7 Task Force Reports

7.1 Electromagnetic Characterization Study Group

No report was provided by the Task Force.

7.2 Packages and Packaging Materials Eco-efficiency Task Force

On behalf of the TF co-leaders, Masahiro Tsuruya, co-chairs of the Packaging Committees, reported for Packages and Packaging Materials Eco-efficiency Task Force. Of note:

- Task Force came to the conclusion that it was inactive anymore and the standardization related Eco and Environment did not give much impact to industry. Therefore TF proposed to sunset the activities.

Motion: To disband Packages and Packaging Materials Eco-efficiency Task Force.

By / 2nd: Yutaka Koma (Consultant) / Sumio Masuchi (Disco)

Discussion: None

Vote: 10 in favor and 0 opposed. **Motion passed.**

Attachment: 06_Packages_and_Packaging_Materials_Eco-efficiency_TF_Report_140320

7.3 Wafer Shipping Container for Assembly & Packaging Task Force

On behalf of the TF co-leaders, Masahiro Tsuruya, co-chairs of the Packaging Committees, reported for Wafer Shipping Container for Assembly & Packaging Task Force. Of note:

- Task Force came to the conclusion that there was no business on wafer shipping container currently. Therefore TF proposed to disband the Task Force.

Motion: To disband Wafer Shipping Container for Assembly & Packaging Task Force.

By / 2nd: Hideki Suzuki (Shin-Etsu Polymer) / Masahiro Tsuruya (iNEMI)

Discussion: None

Vote: 10 in favor and 0 opposed. **Motion passed.**

Attachment: 07_Wafer_Shipping_Container_for_Assembly_and_Packaging_TF_Report_140320

7.4 DFM Study Group

No report was provided by the Task Force.

7.5 450mm Japan Assembly & Test Die Preparation Task Force

Sumio Masuchi reported on progress for 450mm Japan Assembly & Test Die Preparation Task Force. Of note:

- *Doc.#5636, Revision of SEMI G92-0412, Specification for Tape Frame Cassette for 450mm Wafer*, passed committee review as previously discussed. (See 6.1)
- *SEMI G95-0314, Mechanical Interface Specification for 450mm Load Port for Tape Frame Cassettes in the Backend Process*, passed ISC A&R review and published in March.

Attachment: 08_450mm_Japan_Assembly_&_Test_Die_Preparation_TF_Report_140320

7.6 Thin Die Bending Strength Measurement Method Task Force

Haruo Shimamoto reported on progress for the Thin Chip Die Bending Strength Measurement Method Task Force. Of note:

- SNARF and Submission of the letter ballot of *Doc.#5691, New Standard: Test Method for Measurement of Chip (Die) Strength by Mean of Cantilever Bending* for Cycle 2 was approved on January 30 by GCS.
- The result will be reviewed at the committee meeting on May 8.

Attachment: 09_Thin_Die_Bending_Strength_Measurement_Method_TF_Report_140320

7.7 3D-IC Study Group

Masahiro Tsuriya reported on progress for the 3D-IC Study Group. Current achievements are below:

- Held the joint meeting with N.A. and TWN 3DS-IC technical committee to exchange information on Dec 5, 2013.
- Organized the 3D-IC technology seminar during the SEMICON Japan 2013 with very good reputation.
- Exhibited the 3D-IC standards activities and several displays at the SEMICON Japan 2013.
- Conducted the surveys to solicit the inputs from the industries on the potential areas of needs for SEMI Standardization. The summary was shared with the SG team at Jan 23, 2014 meeting.
- Agreed on the formation of Thin Chip Handling TF. Kick-off the TF from April after TC approval on 3/20-2014

Attachment: 10_3D-IC_SG_Report_140320

7.8 Fiducial Mark Interoperability Task Force

Sumio Masuchi reported for the Fiducial Mark Interoperability Task Force. There were no particular progress should be reported since the previous committee meeting. If some proposal about Notch-free will be made at the NA Spring meetings, the activities will start

Attachment: 11_Fiducial_Mark_Interoperability_TF_Report_131111

8 Old Business

8.1 Previous Meeting Action Items

Naoko Tejima reviewed the previous meeting action items.

Table 7 Previous Meeting Actions Items

Item #	Assigned to	Details
PKG120829-2	Committee Co-Chairs	To review the Committee Charter of Japan Packaging Committee Closed
PKG130325-2	3D-IC Study Group	To discuss the contents of SJ2013 Pavilion and Workshop with SEMI Staff Closed
PKG130325-3	SEMI	To publish G92 Related Information Closed
PKG130719-6	SEMI	To check whether there are some documents for 5-year-review procedure. Closed
PKG130719-9	Co-chairs	To review all SNARFs and check whether they are written in the right way. Open
PKG131111-1	SEMI staff	To check the concrete contents of “new activity on unsupported thin wafer handling” to TF. Closed
PKG131111-2	SEMI staff	To get the presentation materials of SEMATECH and to distribute it to JA PKG TC members. Closed
PKG131111-3	SEMI staff	To raise an issue to SPI TF that the respond to reject-voters is different by each region.
PKG131111-4	SEMI staff	To forward adjudication result of Doc.#5637 to the ISC A&R Subcommittee for procedural review. Closed
PKG131111-5	450mm ATDP Task Force	To submit Doc.#5636 for Cycle 1, 2014. Closed
PKG131111-6	SEMI staff	To get some information and materials of MEMS Wafer Bonded TF / MEMS Packaging TF and to distribute it to JA PKG TC members. Closed

Table 7 Previous Meeting Actions Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
PKG131111-7	Kazunori Kato	To convene an ad-hoc co-leaders meeting to review the Committee Charter and all SNARFs, and check whether they are written in the right way of Japan Packaging Committee. (Participants: Kasunori Kato, Yutaka Koma, Masahiro Tsuruya, Nobuo Hayasaka and Haruo Tabata) Closed
PKG131111-8	SEMI staff	To send the list of the documents for 5-year-review procedure to Co-chairs. Closed

9 New Business

9.1 Proposal of setting up Thin Chip Handling Task Force

Hideki Suzuki proposed to newly set up Thin Chip Handling Task Force and TFOF was submitted.

Motion: To set up Thin Chip Handling Task Force.

By / 2nd: Hideki Suzuki (Shin-Etsu Polymer) / Haruo Shimamoto (AIST)

Discussion: None

Vote: 10 in favor and 0 opposed. **Motion passed.**

Attachment: 12_TFOF_of_Thin Chip Handling_TF_140320

Attachment: 13_How_to_proceed_Thin_Chip_Handling_TF_140320

9.2 Proposal of setting up Packaging 5 Year Review Task Force

Masahiro Tsuruya proposed to newly set up Packaging 5 Year Review Task Force and TFOF was submitted.

Motion: To set up Packaging 5 Year Review Task Force.

By / 2nd: Masahiro Tsuruya (iNEMI) / Sumio Masuchi (Disco)

Discussion: None

Vote: 10 in favor and 0 opposed. **Motion passed.**

Action Item: SEMI staff to attach the document list of 5 year procedure review to the meeting minutes.

Attachment: 14_TFOF_of_Packaging_5_Year_Review_TF_140320

Attachment: 15_Document_List_of_5_Year_Review_Procedure_140320

9.3 Review of the Committee Charter of Japan Packaging Committee

Masahiro Tsuruya proposed to review the committee charter of Japan Packaging Committee and presented the revised version.

Motion: To approve to revise Japan Packaging Committee Charter as presented.

By / 2nd: Masahiro Tsuruya (iNEMI) / Hideki Suzuki (Shin-Etsu Polymer)

Discussion: None

Vote: 10 in favor and 0 opposed. **Motion passed.**

Action Item: SEMI staff to submit the new committee charter to JRSC to get their approval.

Attachment: 16_PKG_Committee_Charter_140320



10 Action Item Review

10.1 New Action Items

Naoko Tejima reviewed the new action items. These can be found in the New Action Items table at the beginning of these minutes.

11 Next Meeting and Adjournment

The next meeting of the Japan Packaging Committee is scheduled for Thursday, May 8, 2014, 15:00-17:00, at SEMI Japan, Tokyo, Japan.

Respectfully submitted by:
 Naoko Tejima
 Manager, Standards
 SEMI Japan
 Phone: +81.3.3222.5804
 Email: ntejima@semi.org

Minutes approved by:

Yutaka Koma (Consultant), Co-chair	April **, 2014
Masahiro Tsuruya (iNEMI), Co-chair	April 9, 2014

Table 8 Index of Available Attachments #1

#	<i>Title</i>
1	JA_PKG_Previous_Mtg_Minutes_140320
2	SEMI_Staff_Report_140320
3	NA_3DS-IC_Comm_Report_140320
4	TW_3DS-IC_Comm_Report_140320
5	Ballot_Report_for_5636_140320
6	Packages_and_Packaging_Materials_Eco-efficiency_TF_Report_140320
7	Wafer_Shipping_Container_for_Assembly_and_Packaging_TF_Report_140320
8	450mm_Japan_Assembly_&_Test_Die_Preparation_TF_Report_140320
9	Thin_Die_Bending_Strength_Measurement_Method_TF_Report_140320
10	3D-IC_SG_Report_140320
11	Fiducial_Mark_Interoperability_TF_Report_140320
12	TFOF_of_Thin_Chip_Handling_TF_140320
13	How_to_proceed_Thin_Chip_Handling_TF_140320
14	TFOF_of_Packaging_5_Year_Review_TF_140320
15	Document_List_of_5_Year_Review_Procedure_140320
16	PKG_Committee_Charter_140320

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact Naoko Tejima at the contact information above.